

Product Change Notice (PCN)

Subject: Add Alternate Assembly Location on Select CABGA Package

Publication Date: 3/14/2025

Effective Date: 6/13/2025

Revision Description:

Initial Release

Description of Change:

Renesas is adding ASEC, Taiwan as the alternate Assembly location in expanding the supply chain for select CABGA-100 package. The alternate assembly location is the current qualified location for Renesas. The material sets of the current location and the alternate assembly location are identical as shown in the table below. The process flows are identical at all the qualified assembly locations.

There will be no changes in the moisture sensitive level due to this change.

	Existing	Alternate
Material Set / Assembly	JCET, China	ASEC, Taiwan
Die Attach Epoxy	2100A	2100A
Bonding Wire	Copper Wire	Copper Wire
Mold Compound	EME G760L	EME G760L
Solder Ball	SAC305	SAC305

Affected Product List: Refer Appendix B.

Reason for Change:

The change is to create dual supply to secure business continuity.

Impact on Fit, Form, Function, Quality & Reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the products.

Product Identification:

Assembly lot# prefix denote Assembly Location

Prefix	Current Location	Alternate Location
JC	JCET China	
RC		ASEC Taiwan

Qualification Status: Completed. Refer Appendix A
Sample Availability Date: 16 weeks from sample booking date
Device Material Declaration: Available upon request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results
Affected Package: CABGA-100

Qual Vehicle: CABGA-100

Assembly Material: As shown in page 1

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Test Descriptions	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55 °C to 125 °C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (110 °C/85% RH, 264 Hrs)	JESD22-A110	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150 °C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Ball Shear Test	JESD22-B116	0/5	0/5	0/5
Bond Pull Test	MIL-STD-883 (Method 2011)	0/5	0/5	0/5
Physical Dimensions	JESD22-B100	0/30	0/30	0/30
Die Shear Test	MIL-STD-883 (Method 2019)	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

*Tests were subjected to Preconditioning per JESD22-A113 prior to stress test

Appendix B – Affected Product List

RC35312A100GBB#BC0	RC35312AXXXGBB#HC0	RC38112A2ENGBB#BC0	RC38312A1ENGBB#BC0
RC35312A100GBB#HC0	RC38112A100GBB#BC0	RC38112A2ENGBB#HC0	RC38312A1ENGBB#HC0
RC35312A101GBB#BC0	RC38112A100GBB#HC0	RC38112AXXXGBB#BC0	RC38312A200GBB#BC0
RC35312A101GBB#HC0	RC38112A104GBB#BC0	RC38112AXXXGBB#HC0	RC38312A200GBB#HC0
RC35312A102GBB#BC0	RC38112A104GBB#HC0	RC38312A100GBB#BC0	RC38312A201GBB#BC0
RC35312A102GBB#HC0	RC38112A1ENGBB#BC0	RC38312A100GBB#HC0	RC38312A201GBB#HC0
RC35312A103GBB#BC0	RC38112A1ENGBB#HC0	RC38312A100GBB#KC0	RC38312A204GBB#BC0
RC35312A103GBB#HC0	RC38112A200GBB#BC0	RC38312A101GBB#BC0	RC38312A204GBB#HC0
RC35312A104GBB#BC0	RC38112A200GBB#HC0	RC38312A101GBB#HC0	RC38312A2ENGBB#BC0
RC35312A104GBB#HC0	RC38112A201GBB#BC0	RC38312A102GBB#BC0	RC38312A2ENGBB#HC0
RC35312A200GBB#BC0	RC38112A201GBB#HC0	RC38312A102GBB#HC0	RC38312AXXXGBB#BC0
RC35312A200GBB#HC0	RC38112A204GBB#BC0	RC38312A104GBB#BC0	RC38312AXXXGBB#HC0
RC35312AXXXGBB#BC0	RC38112A204GBB#HC0	RC38312A104GBB#HC0	RC38312AXXXGBB#KC0